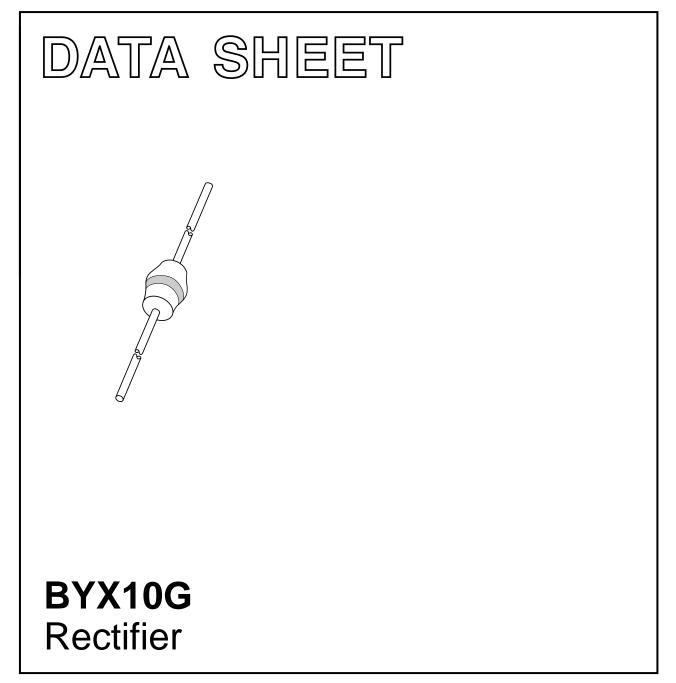
# DISCRETE SEMICONDUCTORS



Product specification File under Discrete Semiconductors, SC01 1996 May 24





## **Product specification**

# BYX10G

### FEATURES

- · Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Available in ammo-pack.

### DESCRIPTION

Rugged glass package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



Fig.1 Simplified outline (SOD57) and symbol.

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RSM</sub>	non-repetitive peak reverse voltage		-	1600	V
V <sub>RRM</sub>	repetitive peak reverse voltage		-	1600	V
V <sub>RWM</sub>	crest working reverse voltage		-	800	V
I <sub>F(AV)</sub>	average forward current	$T_{tp} = 50 ^{\circ}C;$ lead length = 10 mm; averaged over any 20 ms period; see Figs 2 and 4	_	1.2	A
		T <sub>amb</sub> = 60 °C; PCB mounting (see Fig.9); averaged over any 20 ms period; see Figs 3 and 4	_	0.6	A
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sinewave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RWMmax}$	-	25	A
T <sub>stg</sub>	storage temperature		-65	+175	°C
Tj	junction temperature	see Fig.5	-65	+175	°C

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## ELECTRICAL CHARACTERISTICS

 $T_j = 25 \ ^{\circ}C$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 2 A; T_j = T_{j max}$ ; see Fig.6	-	_	1.5	V
		I <sub>F</sub> = 2 A; see Fig.6	-	_	1.5	V
I <sub>R</sub>	reverse current	$V_R = V_{RWMmax}$ ; see Fig.7	-	_	1	μA
		$V_R = V_{RWMmax}$ ; $T_j = 150 \text{ °C}$ ; see Fig.7	-	_	200	μΑ
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.10	_	3	_	μs
C <sub>d</sub>	diode capacitance	$V_R = 0 V$ ; f = 1 MHz; see Fig.8	_	30	—	pF

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	46	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	100	K/W

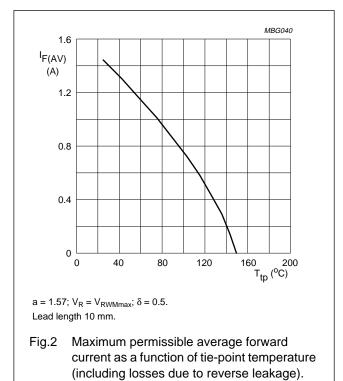
Note

1. Device mounted on epoxy-glass printed-circuit board, 1.5 mm thick; thickness of copper ≥40 μm, see Fig.9. For more information please refer to the *"General Part of Handbook SC01"*.

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Product specification

### **GRAPHICAL DATA**



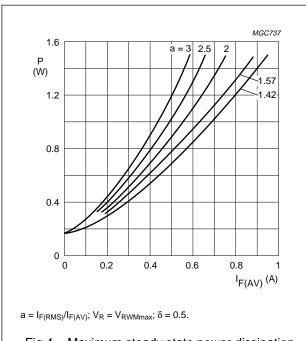
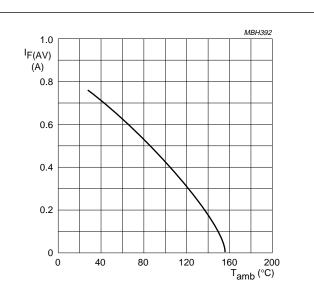
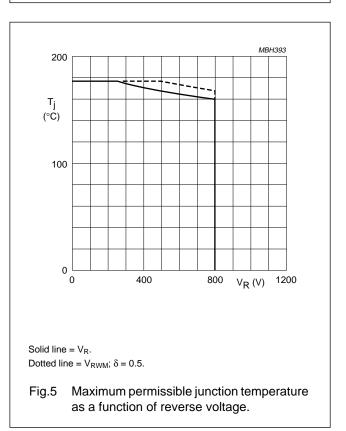


Fig.4 Maximum steady state power dissipation (forward plus leakage current losses, excluding switching losses) as a function of average forward current.

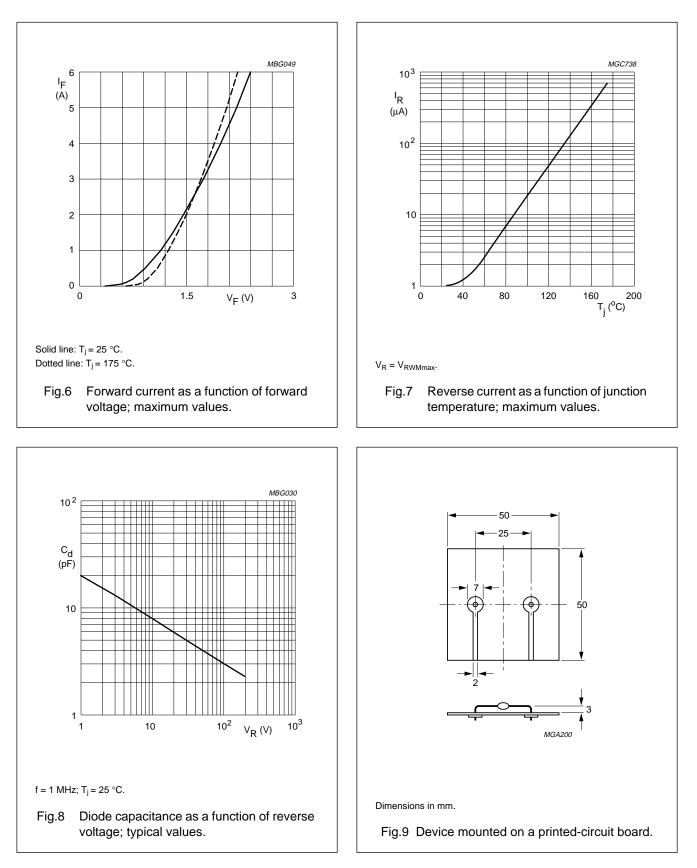


a = 1.57;  $V_R = V_{RWMmax}$ ;  $\delta$  = 0.5. Device mounted as shown in Fig.9.

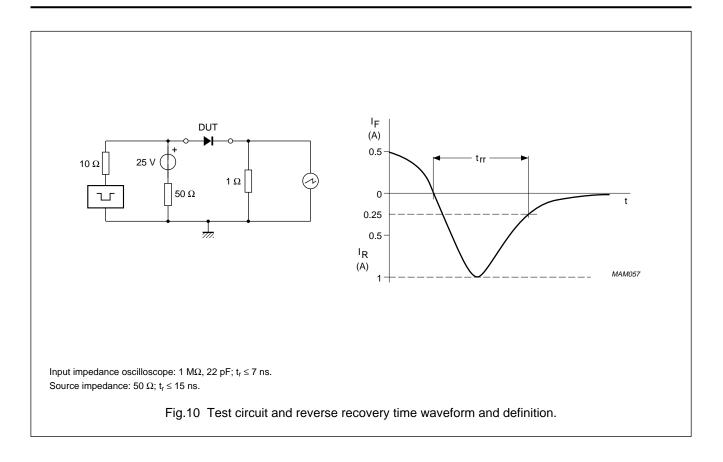
Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).



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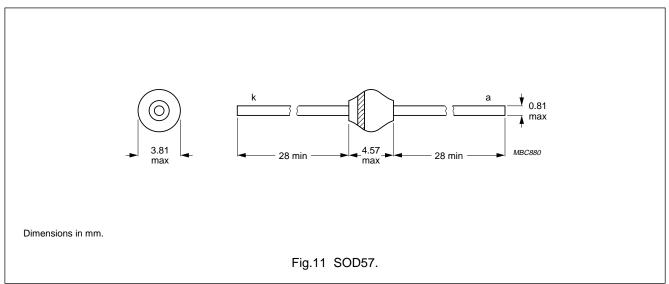


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### PACKAGE OUTLINE



### DEFINITIONS

Data sheet status		
Objective specification	ion This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
more of the limiting values r of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or nay cause permanent damage to the device. These are stress ratings only and operation any other conditions above those given in the Characteristics sections of the specification imiting values for extended periods may affect device reliability.	
Application information		
Where application information	on is given, it is advisory and does not form part of the specification.	

## LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.